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ICIEA 2023

THE 18th IEEE CONFERENCE ON INDUSTRIAL ELECTRONICS AND APPLICATIONS

18 – 22 August 2023, Ningbo, China
<http://www.ieeeciea.org>

The 18th IEEE Conference on Industrial Electronics and Applications (ICIEA 2023) will be held during 18-22 August 2023, in Ningbo, China. The Conference is organized by IEEE Industrial Electronics Chapter of Singapore, NingboTech University, Ningbo Institute of Materials Technology and Engineering, Zhejiang Fashion Institute of Technology and IEEE Singapore Section. IEEE Industrial Electronics Society is the financial and technical sponsor. **The proceedings of past ICIEAs have been included in the IEEE Xplore database and indexed by EI Compendex. ICIEA is ranked in the top 15% of the best conferences in the field of Electronics and Electrical Engineering according to research.com.**

ICIEA 2023 marks the 18th Anniversary of the ICIEA conferences. As a premier conference, ICIEA provides an excellent forum for scientists, researchers, engineers and industrial practitioners throughout the world to present and discuss the latest technology advancement as well as future directions and trends in Industrial Electronics.

Authors are invited to submit full papers describing original research work in areas including, but not limited to:

Artificial Intelligence: Natural language processing & interaction, Text, image & video analysis, Speech recognition, Object recognition, Gesture recognition, Machine learning, Knowledge representation, Reasoning, Statistical learning, Deep learning, Neural networks, Design for AI chip and systems, AI applications

Control and Systems: Adaptive and intelligent control, Hybrid control, Digital control theory and development, Robust control, Nonlinear systems and control, Process control, Networked control, Cooperative control, Bio-control

Cyber-physical Systems: Smart grid, Intelligent transportation systems, Internet of things, Mobile healthcare, Distributed computing, Infrastructure simulations, Security and privacy, Data integration and visualization, New sensing platform and senses computing, Digital twin technologies

Energy and Environment: Energy management and control systems, Energy distribution, storage and recovery, Alternative and green energy, Waste management, Waste treatment and recycling, Water network and security, Sensor technologies, Intelligent micro-grids, Renewable energy, Demand side management, Solar photovoltaic and wind system, Energy meteorology, Green battery, Offshore systems

Industrial Informatics and Computational Intelligence: Human-machine interactions, Diagnosis and prognosis, Intelligent automation, Networked embedded controllers, Machine-to-machine, Condition based maintenance, Multi-agent systems, Fuzzy systems, Genetic algorithm, Evolutionary computing, Data mining

Robotics: Robotics vision, Visual servoing, Visual servoing simulation, SLAM, LIDAR, Sensors and sensor fusion, Actuators, Motion control, Robot-human collaboration, Remote operation, Autonomous mobile robot, Reinforcement learning, 3D simulation, Off-line programming, AI application in robotics, Industrial application case study

Network and Communication Technologies: Network protocols, Mobile computing, Mobile ad hoc networks, Mobile agents, Network architectures, Quality of services, Cross-layer design/optimization, Design and performance evaluation, Traffic control, Wireless systems, MU-MIMO systems, Optoelectronics and Optical Communication

Power Electronics: Power devices and components, Electrical machines and Industrial drives, Power quality control, FACTS, PFC, STATCOM, Harmonic analysis and compensations, Switching circuits and power converters, Motors and drives, Smart grid, Distribution generation and electrical vehicles, Wireless power transmission, Energy harvesting

Signal and Information Processing: Image processing, Computer vision, Bio-image processing, Audio/video processing, Data processing, Estimation and identification, Remote sensing, Information fusion, Brain computer interface, Signal transforming and filtering, Digital system design and structures, Optimization techniques

•**Special Sessions:** The Technical Program Committee is soliciting proposals for special sessions focusing on topics relevant to the theme of the conference. Prospective organizers should submit proposals to the Special Session Chairs led by Dr. Wenxiang Xie (wxie@ieeiee.org) by the date listed in "Important Dates".

•**Workshop on 22 August:** Topics to be determined. Proposals should be submitted to Workshop Chairs for review.

•**Best Paper Award:** The best paper award will be presented at the conference. The winner(s) will be selected based on both technical content and presentation by the Award Committee in consultation with the International Advisory Committee.

Paper Submission: Please submit full papers to the conference website at <http://www.ieeeciea.org>. All submitted papers should be in the form of .pdf or .ps file and are to be limited to a maximum length of 6 pages (Letter size, single space, Times Roman of font size 10, two columns format), including figures, tables and references. Please use the template which is available from the website. Upon acceptance, authors will be required to register and present their papers. Papers will be published in the conference proceedings only if at least one of the authors is officially registered. Each registration covers a maximum of two papers.

In addition to the technical sessions, **KEYNOTE ADDRESSES** and **DISTINGUISHED LECTURES** on the State-of-the-Art in various tracks of Industrial Electronics will be delivered. Details will be announced on website.

Important Dates:

Deadline for Full Paper submission	31 March 2023
Deadline for Invited and Special Sessions	31 March 2023
Notification of Acceptance	30 April 2023
Deadline for Camera Ready Manuscript Submission	31 May 2023
Deadline for Authors' Registration	30 June 2023

